

OL-NX3P191

Wafer level chip-size package.4 bumps; body 0.76 x 0.76 x 0.51 mm. (Backside Coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	10-6-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.71	-	0.76	0.81	mm
E	package width	0.71	-	0.76	0.81	mm
A	seated height	0.48	-	0.51	0.54	mm
A ₂	package height	0.3	-	0.31	0.32	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	4	-	

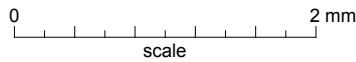
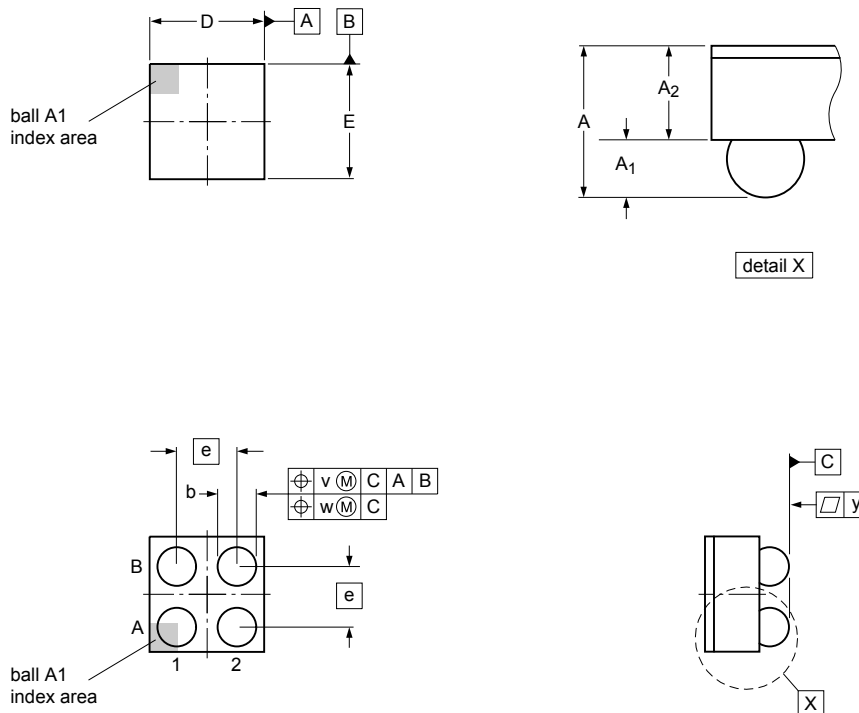


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0.76 x 0.76 x 0.51 mm. (Backside Coating
included)

2. Package outline

WLCSP4: wafer level chip-size package.
4 bumps; body 0.76 x 0.76 x 0.51 mm. (Backside Coating included)

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Dimensions

Unit	A	A ₁	A ₂	b	D	E	e	v	w	y
max	0.54	0.22	0.32	0.29	0.81	0.81				
mm nom	0.51	0.20	0.31	0.26	0.76	0.76	0.40	0.025	0.025	0.03
min	0.48	0.18	0.30	0.23	0.71	0.71				

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX3P190/NX3P191					-11-05-24- 11-06-09

Fig. 1. Package outline WLCSP (OL-NX3P191)

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3. Legal information

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Date of release: 8 February 2016
